| ASSOCIATION CONNECTING LECTRONICS INDUSTRIES INDUSTRIES | C. Bannockł | ourn. Illinois. A | ll rights reserved untions. | under both | This docum level parts, t | ent is a declara he declaration | ion of the s encompasse | ubstances es all lowe | within the m r level mater | anufacturer ials for whi | r listed item. | Note: if the second sec | he item is an as as engineering | sembly with lower responsibility. | |
|---|---|-------------------------------|-----------------------------|--------------------|--|------------------------------------|------------------------------|--------------------------|-------------------------------|-----------------------------|---------------------------------|--|------------------------------------|--------------------------------------|--|
| | IPC Web Site for Information on IPC-1752 Standard Form http://www.ipc.org/IPC-175x Distr | | | | * Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi | | | | | us Material | als and Mfg Information | | | | |
| Supplier Information | | | | | | | | | | | | | | | |
| Company name* | Company un | Company unique ID | | | Unique ID Authority | | | | | Response Date* | | | | | |
| nsemi | | | | | | | | | | 2 | 2025-05-10 | | | | |
| Contact Name | tact Name Title - Contact | | | Phone - Contact* | | | Email | | | Email - Cont | ail - Contact* | | | | |
| Product-Env-Stewards Product | | | duct Enviro Compliance | | | NA | | | | | Product-Env-Stewards@onsemi.com | | | | |
| Authorized Representative* Title - Represe | | | sentative | | | Phone - Representative* | | | | 1 | Email - Representative* | | | | |
| Product-Env-Stewards Produ | | | Product Enviro Compliance | | | NA | | | | | Product-Env-Stewards@onsemi.com | | | | |
| Requester Item Number | Mfr Item | n Number | Mfr Item Name | | | Effective Dat | e Version |] | Manufacturing Site | | Weig | ht* | UOM | Unit Type | |
| | NRVTS G | RVTS1260EMFST1 60V Low Leakag | | e Trench Rectifier | | 2025-05-10 | |] | MY1 | | 113.0 | 69 | mg | Each | |
| Manufacturing Proccess Informati | on | | | | | | | | | | | | | | |
| Terminal Plating / Grid Array Mate | erial 7 | ial Terminal Base Alloy | | J-STD-020 MSI | TD-020 MSL Rating | | Peak Process Body Temperatur | | e Max Time at Peak Temper | | emperature | Number | of Reflow Cyc | les | |
| Matte Tin (Sn) - annealed CU Alloy | | | | 1 | | 260 | | С | 30 | | seconds | 3 | | | |
| Comments | | | | | | | | | | | | | | | |
| evel 1 - maximum time at peak temperatur | e during so | Idering is 10-3 | 0 seconds | | | | | | | | | | | | |
| For more information regarding material c | omposition | please refer to | page 3 | | | | | | | | | | | | |

| RoHS Material Composition Declaration | | | | Declaration Type * | Detailed | | | | |
|--|---|--|---|---|---|--|--|--|--|
| Directive 2015/863/EU amending RoHS Directive 2011/65/EU | | mium (Cr6+), Polybrominated Biphenyls (Pl | | dmium and quantity limit of 0.1% by mass (10 minated Diphenyl Ethers (PBDE), and Bis(2-et | | | | | |
| cadmium, hexavalentchromium, polybromina contains a RoHS restricted substance inexces encompass all such components. Supplier cer as of the date that Supplier completes this for Company acknowledges that Supplier may h independently verified information provided certification in this paragraph. If the Company | ated biphenyls and/or polybrominated dip s of an applicable quantity limit, please in ifies that it gathered the information it pr m.Supplier acknowledges that Company ave relied on informationprovided by oth by others, Supplier agrees that, at a minir and the Supplier enter into a written agr esource of the Supplier's liability and the | henyl ethers (each a "RoHS restricted substa ndicate below which, if any, RoHS exemption ovides in this form using appropriate methoo will rely on this certification in determining ers in completing this form, and that Supplie num, itssuppliers have provided certification eement with respect to the identified part, the Company's remedies for issues that arise reg | nce") in exco n you believe ls to ensure i the compliar r may not ha s regarding t terms and co | e may apply. If the part is an assembly with low s accuracy and that such information is true an ce of its products with European Union member de independently verified such information. Ho neir contributions to the part, and those certifica | ove. If a homogeneous material within the part er level components, the declaration shall d correct to the best of its knowledge and belief, er state laws that implement the RoHS Directive. wever, in situations where Supplier has not ations are at least as comprehensive as the anty rights and/or remedies provided as part of | | | | |
| RoHS Declaration * 4 - Item(| s) does not contain RoHS restricted subst | ances per the definition above except for sele | ected exempt | ions Supplier Acceptance | * Accepted | | | | |
| Exemption: 7a: Lead in high melting temp | erature type solders (i.e. lead based sol | der alloys containing 85% by weight or m | ore lead). | | | | | | |
| Exemption List Version | EL-2011/534/EU | | | | | | | | |
| Declaration Signature | | | | | | | | | |
| Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester. | | | | | | | | | |
| Supplier Digital Signature | astislav Drska | Le | | | | | | | |

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

| Homogeneous Material | Weight | Unit of Measure | Level | Substance | CAS | Exempt | Weight | Unit of Measure |
|----------------------|--------|-----------------|----------|-------------------------|------------------|--------|---------|-----------------|
| Clip | 4.8 | mg | Supplier | Zinc (Zn) | 7440-66-6 | | 0.0058 | mg |
| | | | Supplier | Iron (Fe) | 7439-89-6 | | 0.1128 | mg |
| | | | Supplier | Copper (Cu) | 7440-50-8 | | 4.68 | mg |
| | | | Supplier | Phosphorus (P) | 7723-14-0 | | 0.0014 | mg |
| Die | 0.713 | mg | Supplier | Silicon (Si) | 7440-21-3 | | 0.713 | mg |
| Die Attach Solder | 11.9 | mg | Supplier | Silver (Ag) | 7440-22-4 | | 0.2975 | mg |
| | | | А | Lead (Pb) | 7439-92-1 | 7a | 11.0075 | mg |
| | | | Supplier | Tin (Sn) | 7440-31-5 | | 0.595 | mg |
| Lead Frame | 47.44 | mg | Supplier | Iron (Fe) | 7439-89-6 | | 0.0474 | mg |
| | | | Supplier | Copper (Cu) | 7440-50-8 | | 47.3783 | mg |
| | | | Supplier | Phosphorus (P) | 7723-14-0 | | 0.0142 | mg |
| ead Frame plating | 0.13 | mg | Supplier | Silver (Ag) | 7440-22-4 | | 0.13 | mg |
| Mold Compound-Black | 47.136 | mg | | Epoxy resin | proprietary data | | 3.5352 | mg |
| | | | Supplier | Phenolic Resin | Proprietary Data | | 1.1784 | mg |
| | | | Supplier | Silica Amorphous (SiO2) | 7631-86-9 | | 3.5352 | mg |
| | | | Supplier | Carbon Black (C) | 1333-86-4 | | 0.2357 | mg |
| | | | Supplier | Fused Silica (SiO2) | 60676-86-0 | | 38.6515 | mg |
| Plating | 0.95 | mg | Supplier | Tin (Sn) | 7440-31-5 | | 0.95 | mg |